

Title (en)
METHOD FOR ELECTROLESS NICKEL PLATING

Title (de)
VERFAHREN ZUR CHEMISCHEN VERNICKELUNG

Title (fr)
PROCEDE DE DEPOT AUTOCATALYTIQUE DE NICKEL

Publication
EP 1343921 B1 20050316 (EN)

Application
EP 01992803 A 20011004

Priority
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Abstract (en)
[origin: WO0236853A1] A method for electroless metal plating of substrates, more specifically with electrically non-conductive surfaces, by which the substrates may be reliably metal plated at low cost under manufacturing conditions as well and by means of which it is possible to selectively coat the substrates to be treated only, and not the surfaces of the racks. The method involves the following steps: a. pickling the surfaces with a solution containing chromate ions; b. activating the pickled surfaces with a silver colloid containing stannous ions; c. treating the activated surfaces with an accelerating solution in order to remove tin compounds from the surfaces; and d. depositing, by means of an electroless nickel plating bath, a layer that substantially consists of nickel to the surfaces treated with the accelerating solution, the electroless nickel plating bath containing at least one reducing agent selected from the group comprising borane compounds.

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